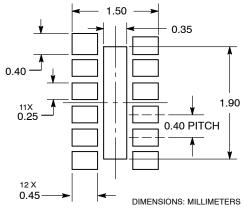


SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

UDFN12 2.5x1.2, 0.4P

DATE 23 OCT 2012

- NOTES: 1. DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
 COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.45	0.50	0.55	
A1	0.00	0.03	0.05	
А3	0.127 REF			
b	0.15	0.20	0.25	
D	2.50 BSC			
D2	1.70	1.80	1.90	
Е	1.20 BSC			
E2	0.20	0.30	0.40	
е	0.40 BSC			
K	0.20 TYP			
L	0.20	0.25	0.30	
L1			0.10	

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code = Month Code Μ

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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